

IN THE CLAIMS:

(1) Please amend Claim 1 as follows:

A1
1. (Amended) An integrated circuit die including first and second sets of conductive pads for enabling external connections to be made to the integrated circuit, wherein each pad of said first set is larger than each pad of said second set, there being at least a first predetermined center-to-center spacing between each pad of the first set and the adjacent pad or pads of the first set, and at least a second predetermined center-to-center spacing, less than said first spacing, between each pad of the second set and the adjacent pad or pads of the first and second sets, and a passivation layer exposing only pads of the first set, or exposing pads of the first and second sets.

(2) Please amend Claim 8 as follows:

A2
8. (Amended) An integrated circuit die, comprising:
a first set of conductive pads having a first minimum distance therebetween; and
a second set of conductive pads having a second minimum distance therebetween, and
between a pad of the second set and a neighboring pad of the first set, wherein each pad of said first set is larger than each pad of said second set;
wherein the die is adapted for selective use as one of a flip-chip assembly and a wire bond.

(3) Please amend Claim 10 as follows:

A3
10. (Amended) A die as recited in claim 8, further comprising a passivation layer for use of the die as a wire bond assembly.

(4) Please add new Claim 11 as follows:

ay --11. (New) An integrated circuit die including first and second sets of conductive pads for enabling external connections to be made to the integrated circuit, there being at least a first predetermined center-to-center spacing between each pad of the first set and the adjacent pad or pads of the first set, and at least a second predetermined center-to-center spacing, less than said first spacing, between each pad of the second set and the adjacent pad or pads of the first and second sets, wherein the pads of the first set are disposed in two lines adjacent one or more edges of the die, the pads of the first set in one of the two lines being disposed in staggered relationship with respect to the pads of the first set in the other of the two lines, and a passivation layer exposing only pads of the first set, or exposing pads of the first and second sets.--

(5) Please add new Claim 12 as follows:

--12. (New) A die as claimed in Claim 11 wherein the pads of the second set are disposed in one of the two lines.--

REMARKS/ARGUMENTS

The Applicants have carefully considered this application in connection with the Examiner's Action and respectfully request reconsideration of this application in view of the foregoing amendment and the following remarks.

The Applicants originally submitted Claims 1-10 in the application. The Applicants presently amend Claims 1, 8 and 10 and add Claims 11 and 12. Accordingly, Claims 1-12 are currently pending in the application.